

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3889521

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CORRECT THE ASSIGNEE NAME FROM TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. previously recorded on Reel 038434 Frame 0461. Assignor(s) hereby confirms the ASSIGNOR(S) CONFIRMS CORRECTION OF ASSIGNEE NAME ON NOTICE OF RECORDATION COVER TO TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD..

CONVEYING PARTY DATA

Name	Execution Date
WEN-HAN LAI	03/18/2016
CHING-YU CHANG	03/18/2016

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6,
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15071243

CORRESPONDENCE DATA

Fax Number: (214)651-5940

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-651-5000

Email: ipdocketing@haynesboone.com

Correspondent Name: HAYNES AND BOONE, LLP IP SECTION

Address Line 1: 2323 VICTORY AVENUE

Address Line 2: SUITE 700

Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.3346US01
NAME OF SUBMITTER:	LADONNA JOHNSON
SIGNATURE:	/LaDonna Johnson/
DATE SIGNED:	05/25/2016

Total Attachments: 5

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT3854417

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>WEI-HAN LAI</td> <td>03/18/2016</td> </tr> <tr> <td>CHING-YU CHANG</td> <td>03/18/2016</td> </tr> </tbody> </table>		Name	Execution Date	WEI-HAN LAI	03/18/2016	CHING-YU CHANG	03/18/2016
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CHING-YU CHANG	03/18/2016						
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State/Country:	TAIWAN						
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Phone:	214-651-5000						
Email:	ipdocketing@haynesboone.com						
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Address Line 2:	SUITE 700						
Address Line 4:	DALLAS, TEXAS 75219						
ATTORNEY DOCKET NUMBER:	24061.3346US01						
NAME OF SUBMITTER:	LADONNA JOHNSON						
SIGNATURE:	/LaDonna Johnson/						
DATE SIGNED:	05/02/2016						
Total Attachments: 2							
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source=Assignment#page2.tif							

ASSIGNMENT

WHEREAS, we,

- (1) Wei-Han Lai of 2F., No. 54, Jinbault St., Jinshan Dist.
New Taipei City 208, Taiwan, R.O.C.
- (2) Ching-Yu Chang of No. 17, Hsinchen Road
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

METHOD OF PRIMING PHOTORESIST BEFORE APPLICATION OF A SHRINK MATERIAL IN A LITHOGRAPHY PROCESS

for which we have filed an application for Letters Patent of the United States of America on March 16, 2016, and assigned U.S. Serial number 15/071,243; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and

Docket No.: 20151418US0/24061.3346US1
Customer No.: 42717

testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Wei-Han Lai

Residence Address: 2F., No. 54, Jinbault St., Jinshan Dist.
New Taipei City 208, Taiwan, R.O.C.

Dated: 2016. 3. 18

Wei-Han Lai
Inventor Signature

Inventor Name: Ching-Yu Chang

Residence Address: No. 17, Hsinchen Road
Hsin-Chu, Taiwan, R.O.C.

Dated: 2016, 3/18

Ching-Yu Chang
Inventor Signature